



VMDSEMI

VUTA003R028NA

Datasheet



VMDSEMI

General Description
Symbol

| | | |
|---------------|--------------------|-------|
| $V_{(BR)DSS}$ | $R_{DS(ON)_{max}}$ | I_D |
| 30V | 2.8mΩ@10V | 150A |
| | 3.5mΩ@4.5V | |

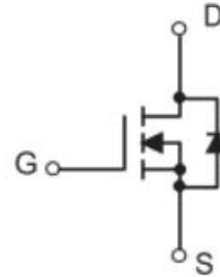
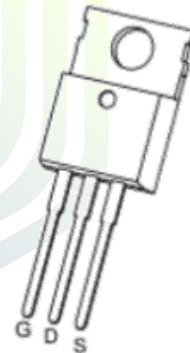


Figure 1 Symbol of VUTA003R028NA

Features

- Trench Technology Power MOSFET
- Low Gate Charge
- Low Gate Resistance
- Low $R_{DS(ON)}$
- 100% UIS Tested

Package Type

TO-220-3L-C
Application

- Power Switch Application
- DC/DC Converter

Figure 2 Package Type of VUTA003R028NA

Ordering Information

| Product Name | Package |
|---------------|-------------|
| VUTA003R028NA | TO-220-3L-C |

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

| Parameter | Symbol | Rating | Unit | |
|---|-----------|----------------------|------|---|
| Drain-Source Voltage | V_{DSS} | 30 | V | |
| Gate-Source Voltage | V_{GSS} | ± 20 | V | |
| Continuous Drain Current ^{Note1} | I_D | 150 | A | |
| Pulsed Drain Current ^{Note2} | I_{DM} | 600 | | |
| Avalanche Current ^{Note3} | I_{AS} | 51 | A | |
| Single Pulsed Avalanche Energy ^{Note3} | E_{AS} | 1300 | mJ | |
| Total Power Dissipation ^{Note5} | P_D | $T_C = 25\text{ °C}$ | 34.7 | W |
| Total Power Dissipation ^{Note5} | | $T_A = 25\text{ °C}$ | 2.1 | |
| Junction Temperature | T_J | 150 | °C | |
| Storage Temperature | T_{STG} | -55 to 150 | °C | |

Thermal Resistance

| Parameter | Symbol | Min | Typ | Max | Unit |
|--|-----------------|-----|-----|-----|------|
| Thermal Resistance, Junction-to-Ambient ^{Note6} | $R_{\theta JA}$ | | 60 | | °C/W |
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | | 3.6 | | °C/W |

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
|--|--------------|-------------------------------|-----|-------|-----------|---------|
| Statistic Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=250\mu A$ | 30 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=30V, V_{GS}=0V$ | | | 1 | μA |
| Gate-Body Leakage Current | I_{GSS} | $V_{GS} = \pm 20V, V_{DS}=0V$ | | | ± 100 | nA |
| Gate Threshold Voltage ^{Note4} | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A$ | 1.0 | 1.5 | 3.0 | V |
| Static Drain-Source On-Resistance ^{Note4} | $R_{DS(on)}$ | $V_{GS}=10V, I_D=20A$ | | 1.7 | 2.8 | mΩ |
| | | $V_{GS}=4.5V, I_D=10A$ | | 2.1 | 3.5 | |
| Forward Transconductance ^{Note4} | g_{FS} | $V_{DS}=5V, I_D=20A$ | | 100 | | S |
| Dynamic Characteristics | | | | | | |
| Input Capacitance | C_{ISS} | $V_{DS}=15V$ | | 7741 | | pF |
| Output Capacitance | C_{OSS} | $V_{GS}=0V$ | | 972 | | pF |
| Reverse Transfer Capacitance | C_{RSS} | $f=1MHz$ | | 849 | | pF |
| Total Gate Charge | Q_g | $V_{DS}=15V$ | | 141.9 | | nC |
| Gate-Source Charge | Q_{gs} | $V_{GS}=10V$ | | 18.5 | | |
| Gate-Drain Charge | Q_{gd} | $I_D=10A$ | | 24.6 | | |
| Gate Resistance | R_g | $f=1MHz, \text{Open drain}$ | | 1.6 | | Ω |
| Switching Parameters | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=20V$ | | 19 | | ns |
| Turn-on Rise Time | t_r | $V_{GS}=10V$ | | 7 | | |
| Turn-off Delay Time | $t_{d(off)}$ | $R_L=1.0\Omega$ | | 69 | | |
| Turn-off Fall Time | t_f | $R_G=3\Omega$ | | 10 | | |
| Diode Characteristics | | | | | | |
| Diode Forward Voltage ^{Note4} | V_{SD} | $V_{GS}=0V, I_S=10A$ | | | 1.2 | V |

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD}=25V, V_{GS}=10V, L=1.0mH, R_G=25\Omega$ Starting $T_J=25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)}=150^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$.

Typical Performance Characteristics

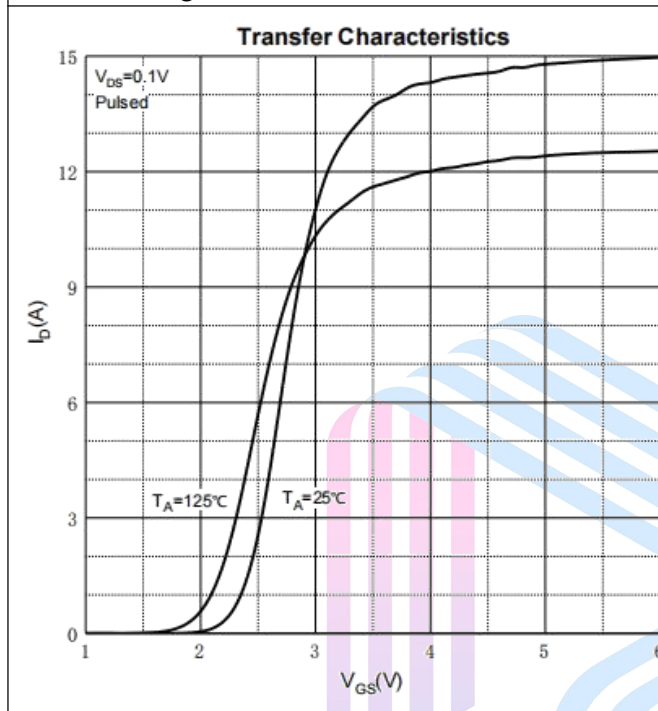
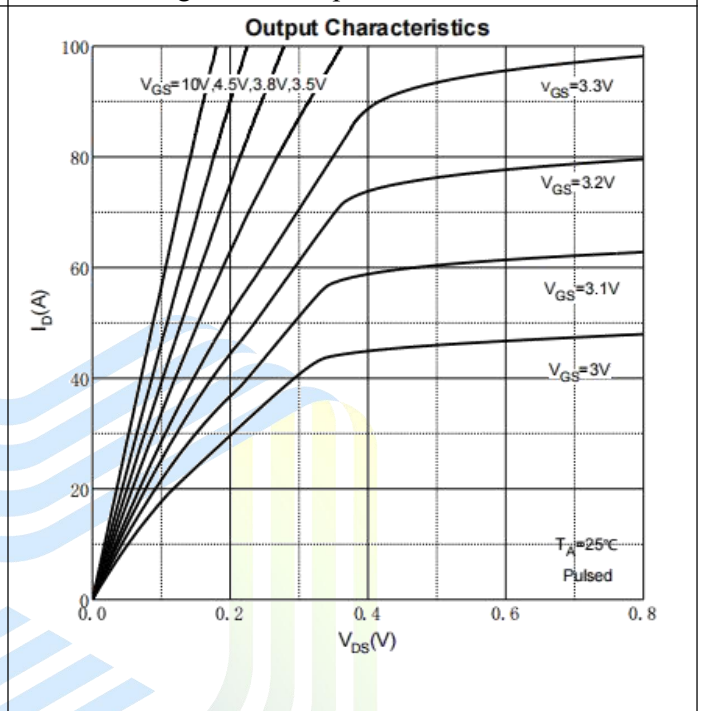
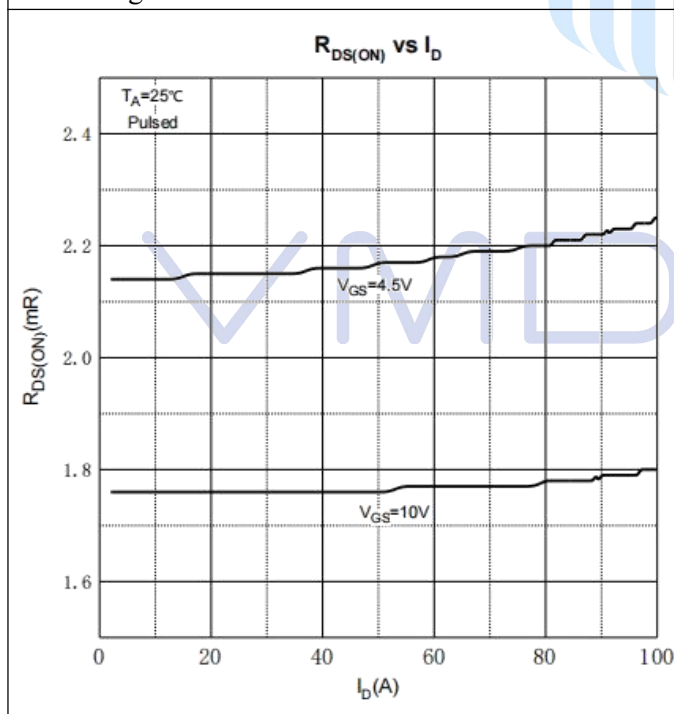
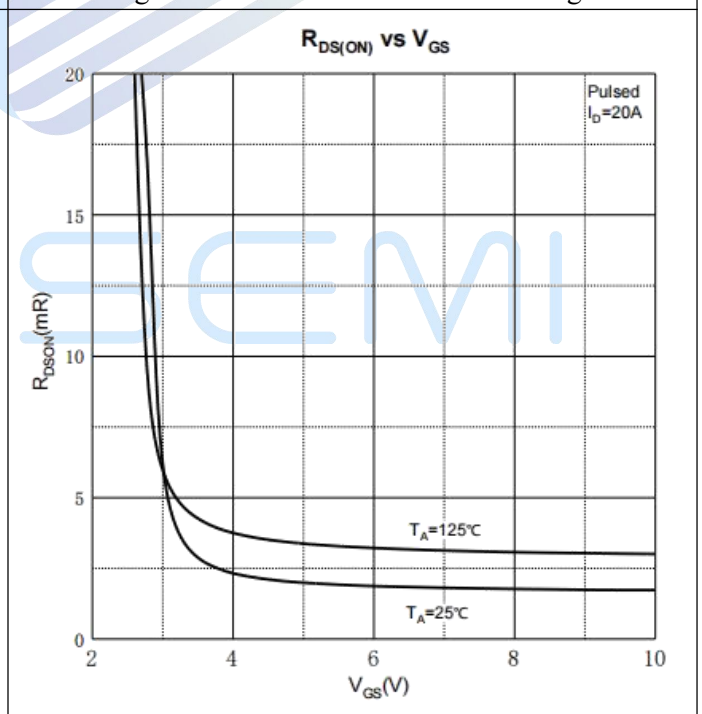
Figure 3: Transfer Characteristics

Figure 4: Output Characteristics

Figure 5: On-Resistance vs. Drain Current

Figure 6: On-Resistance vs. Gate Voltage


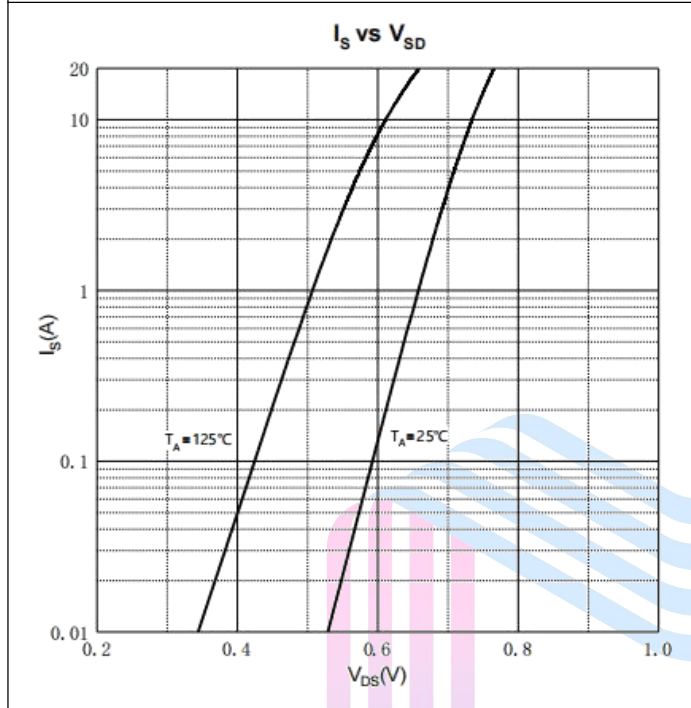
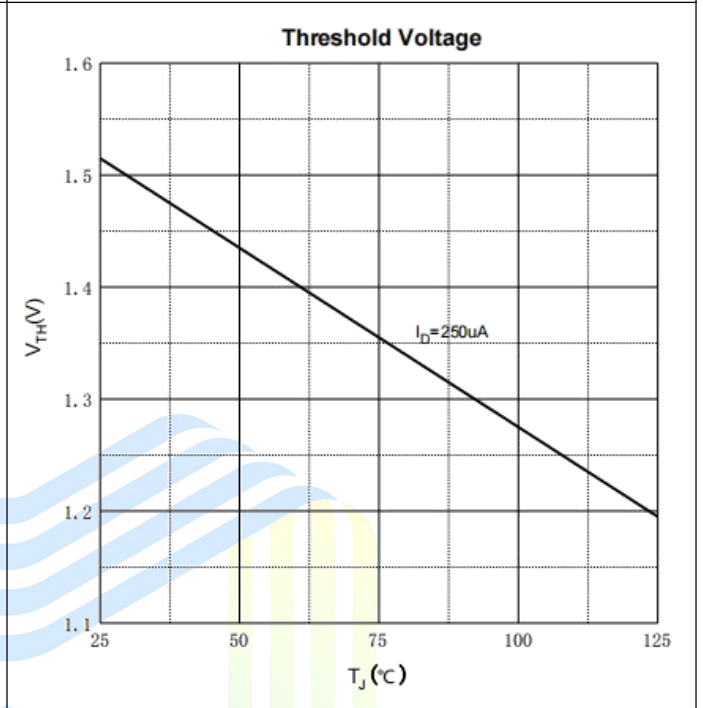
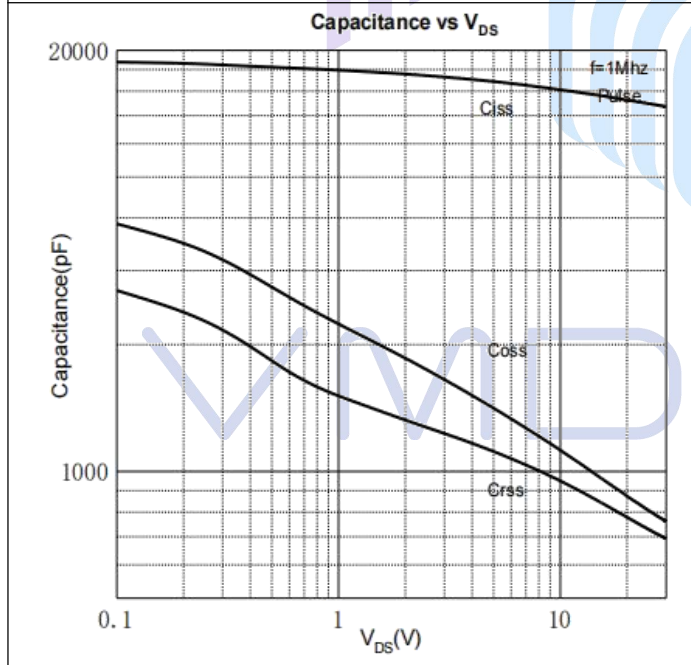
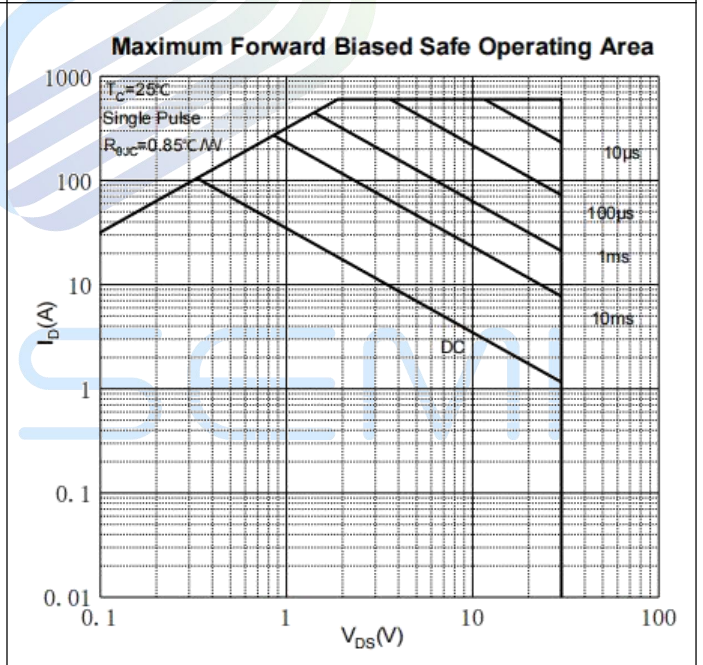
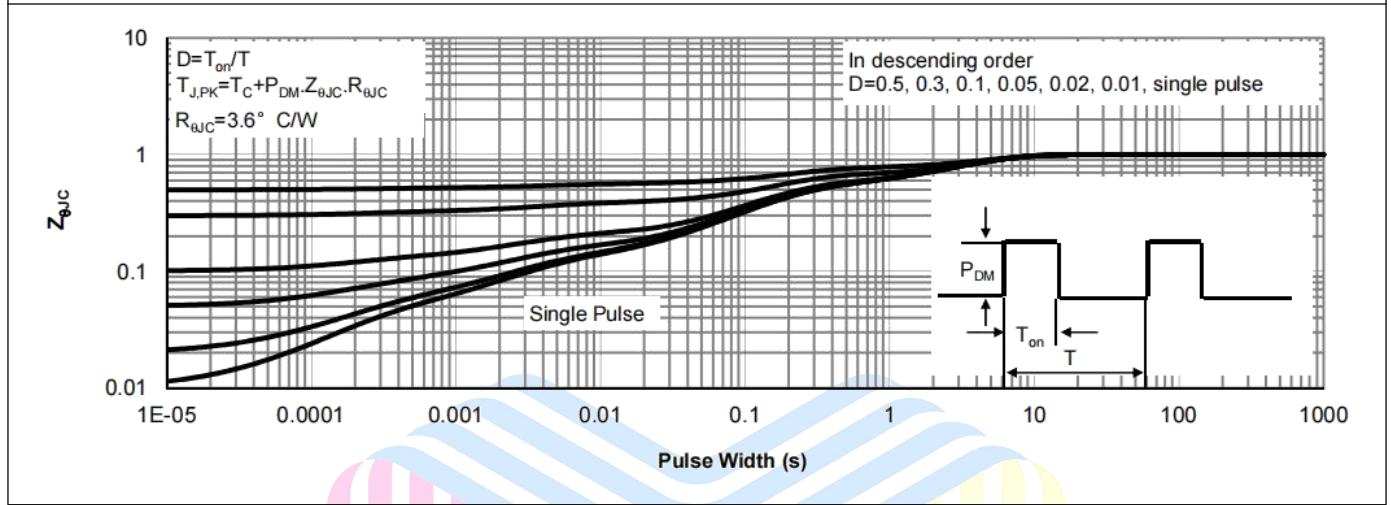
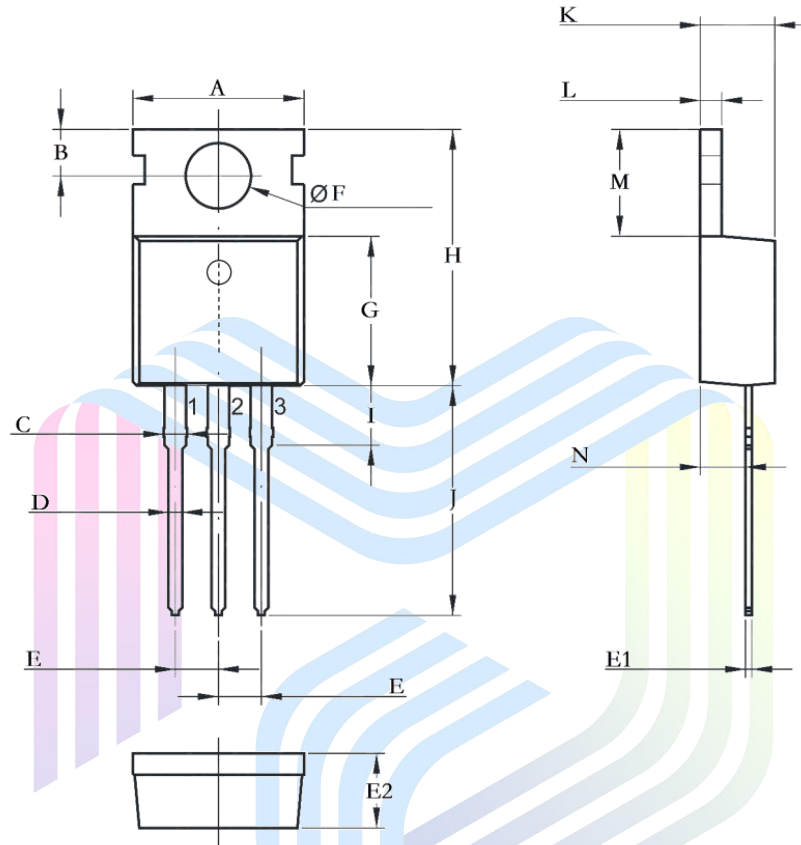
Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage

Figure 9: Typical Capacitance

Figure 10: Safe Operating Area


Figure 11: Normalized Maximum Transient Thermal Impedance



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Mechanical Dimensions:
TO-220-3L-C Package Information


| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 9.600 | 10.400 | 0.378 | 0.409 |
| B | 2.800TYP | | 0.110TYP | |
| C | 1.200 | 1.600 | 0.047 | 0.063 |
| D | 0.600 | 1.000 | 0.024 | 0.039 |
| E | 2.540TYP | | 0.100TYP | |
| E1 | 0.300 | 0.700 | 0.012 | 0.028 |
| E2 | 4.300 | 4.700 | 0.169 | 0.185 |
| F | 3.400 | 4.000 | 0.134 | 0.157 |
| G | 8.850 | 9.350 | 0.348 | 0.368 |
| H | 14.600 | 16.100 | 0.575 | 0.634 |
| I | 2.800 | 4.200 | 0.110 | 0.165 |
| J | 12.600 | 14.800 | 0.496 | 0.583 |
| K | 4.300 | 4.700 | 0.169 | 0.185 |
| L | 1.000 | 1.400 | 0.039 | 0.055 |
| M | 5.840 | 7.000 | 0.230 | 0.276 |
| N | 1.800 | 2.900 | 0.071 | 0.114 |

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Via-Media Semiconductor Limited Company

<http://www.vmdsemi.com>

Main Sites:

- Headquarters

Hangzhou Via-Media Semiconductor Co., LTD.
1305-1306, Building 71, No. 90, Wensan Road, Xihu
District, Hangzhou, Zhejiang Province, P.R. China
Tel: +86-0571-8515 0563

- Chengdu Office

Chengdu Winhi Semiconductor Co., LTD.
Floor 15, Building 5, No. 171, Hele 2nd Street,
Chengdu, Sichuan Province, P.R. China
Tel: +86-028-8505 0771

- Shanghai

Shanghai R&D Center.
1506~1508, Xinyin Building, 888 Yishan Road,
Shanghai, P.R of China
Tel: +86- 021-54201999

- Shenzhen

Shenzhen Sales office
Room 4A15, Block AB, Tianxiang Building,
Chegongmiao , Futian District, Shenzhen, P.R of China
Tel: +86-0755- 82570682

- Xi'an

Xi'an R&D Center
1703B, Building A, Greenland Center, Jinye Road,
High-Tech Zone, Xi'an, Shaanxi, P.R of China